





(0.635 mm) .025"

# **HIGH-SPEED GROUND PLANE SOCKET**

### **SPECIFICATIONS**

For complete specifications and recommended PCB layouts see www.samtec.com?QSS

Insulator Material: Liquid Crystal Polymer Contact Material: Phosphor Bronze

Phosphor Bronze
Plating:
Au or Sn over
50 µ" (1.27 µm) Ni
Current Rating:

Contact: 1.8 A per pin (2 pins powered) Ground Plane: 23.1 A per ground plane (1 ground plane powered) Operating Temp: -55 °C to +125 °C Voltage Rating:

285 VĂC Max Cycles:

RoHS Compliant: Yes



Lead-Free Solderable:

SMT Lead Coplanarity: (0.10 mm) .004" max (025-050) (0.15 mm) .006" max (075)\* \*(.004" stencil solution may be available; contact IPG@samtec.com)

Board Stacking:

For applications requiring more than two connectors per board contact ipg@samtec.com

#### **RECOGNITIONS**

For complete scope of recognitions see www.samtec.com/quality



#### ALSO AVAILABLE (MOQ Required)

- 11 mm & 16 mm stack height
- 30 μ" (0.76 μm) Gold
- Differential Pair and "Partitionable" (combine differential & single-ended banks in same connector) available.
- 100 & 125 positions per row
- Edge Mount
- –LS2 Locking screw hole for QTS–RA–LS2

(3.63)

.143

#### Note

Some lengths, styles and options are non-standard, non-returnable.

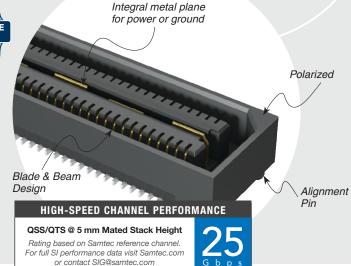


Cable Mates:

Standoffs:









two-piece power/signal solutions

01 PLATING OPTION

.035

**D** 

= Gold Flash on Signal Pins and

Ground Plane, Matte Tin on tails

= 10 μ" (0.25 μm) Gold on Signal Pins

\_ A \_

-GP = Guide Holes for mating

**OTHER** 

**OPTION** 

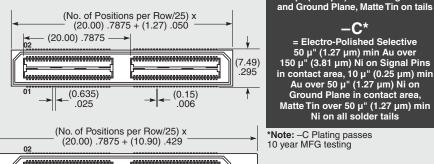
with QTS-RA

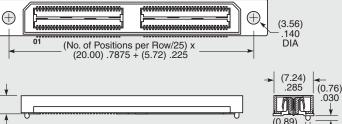
= (8.25 mm) .325" DIA Polyimide Film Pick &

> **−TR** =Tape & Reel

Place Pad

## -025, -050, -075(50 total positions per bank)





QTS LEAD STYLE	MATED HEIGHT WITH QSS
-01	(5.00) .197
-02	(8.00) .315

Processing conditions will affect mated height. See SO Series for board space tolerances

Due to technical progress, all designs, specifications and components are subject to change without notice